P-Channel 20 V (D-S) MOSFET

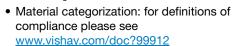


Marking Code: BUxx

PRODUCT SUMMARY				
V _{DS} (V)	-20			
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.035			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.040			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -2.5 \text{ V}$	0.060			
Q _g typ. (nC)	7.0			
I _D (A) ^a	-3			
Configuration	Single			

FEATURES

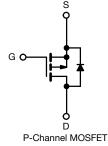
- TrenchFET® gen V p-channel MOSFET
- 100 % R_g and UIS tested





APPLICATIONS

- · Load switches
- DC/DC converters
- · Power management
- LED backlighting



ORDERING INFORMATION	
Package	SOT-363
Lead (Pb)-free and halogen-free	Si1425DH-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T	_A = 25 °C, unles	ss otherwise	noted)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-20	V
Gate-source voltage		V_{GS}	± 12	V
Continuous drain current (T _J = 150 °C) ^a	T _F = 25 °C	I _D	-3 ^a	
	T _F = 70 °C		-3 ^a	
	T _A = 25 °C		-3 a, b, c	A
	T _A = 70 °C		-3 a, b, c	
Pulsed drain current (V _{GS} = 10 V, t = 100 μs)		I _{DM}	-12	
Continuous source-drain diode current	T _F = 25 °C	Is	-2.5	A
	T _A = 25 °C		-1.4 ^{b, c}	_ ^
Maximum power dissipation ^a	T _F = 25 °C	P _D	2.8	
	T _F = 70 °C		1.8	14/
	T _A = 25 °C		1.6 ^{b, c}	W
	T _A = 70 °C		1.0 b, c	
Operating junction and storage temperature range	e	T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t ≤ 5 s	R_{thJA}	60	80	°C/W	
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	34	45		

Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- d. Maximum under steady state conditions is 125 °C/W



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•	•		
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-20	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = -10 mA	-	-14.2	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	3.2	-		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.6	-	-1.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current		V _{DS} = -20 V, V _{GS} = 0 V	-	-	-1	1 .	
	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	μA	
		$V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$	-	0.027	0.035	1	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -3 \text{ A}$	-	0.031	0.043	Ω	
		V _{GS} = -2.5 V, I _D = -2 A	-	0.040	0.060		
Forward transconductance	9 _{fs}	V _{DS} = -10 V, I _D = -6 A	-	20	-	S	
Dynamic ^b			L			L	
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	-	730	-	pF	
Output capacitance	C _{oss}		-	125	-		
Reverse transfer capacitance	C _{rss}		-	100	-		
		V _{DS} = -10 V, V _{GS} = 10 V, I _D = -10 A	-	15	23	nC	
Total gate charge	Q_g		-	7	11		
Gate-source charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 2 \text{ A}$	-	1.8	-		
Gate-drain charge	Q _{gd}		-	1.8	-		
Gate resistance	R _g	f = 1 MHz	1.3	6.5	13	Ω	
Turn-on delay time	t _{d(on)}		-	12	25	- ns	
Rise time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 1 \Omega$	-	32	65		
Turn-off delay time	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	22	45		
Fall time	t _f		-	10	20		
Turn-on delay time	t _{d(on)}		-	7	15	ns	
Rise time	t _r	$V_{DD} = -10 \text{ V}, R_1 = 1 \Omega$	-	5	10		
Turn-off delay time	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	19	40		
Fall time	t _f		-	7	15		
Drain-Source Body Diode Characterist	ics						
Continous source-drain diode current	I _S	T _C = 25 °C	-	-	-2.5	_	
Pulse diode forward current ^a	I _{SM}		-	-	-12	A	
Body diode voltage	V _{SD}	$I_S = -5 \text{ A}, V_{GS} = 0 \text{ V}$	-	-0.85	-1.1	V	
Body diode reverse recovery charge	Q _{rr}		-	2.5	5	nC	
Body diode reverse recovery time	t _{rr}	l _F = -10 A, dl/dt = 100 A/μs,	-	8	20	ns	
Reverse recovery fall time	t _a	T _J = 25 °C	-	5	-		

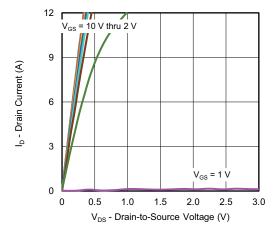
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

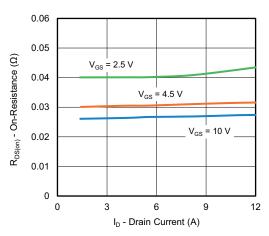
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



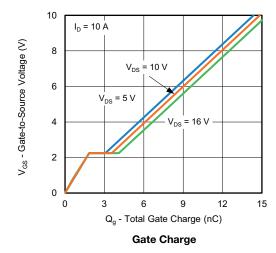
TYPICAL CHARACTERISTICS (T_A= 25 °C, unless otherwise noted)

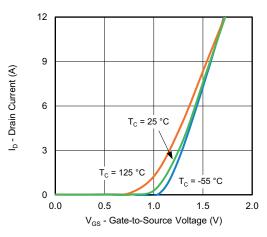


Output Characteristics

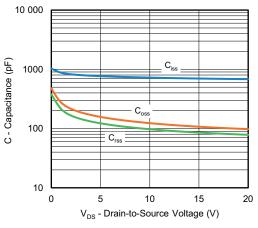


On-Resistance vs. Drain Current

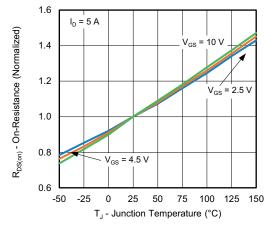




Transfer Characteristics Curves vs. Temperature



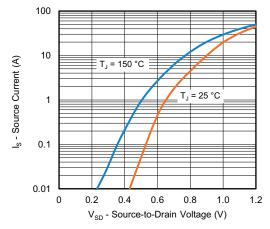
Capacitance



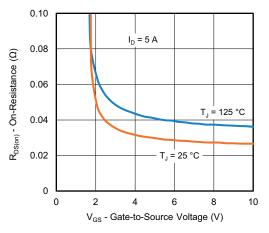
On-Resistance vs. Junction Temperature



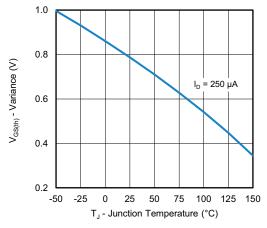
TYPICAL CHARACTERISTICS (T_A= 25 °C, unless otherwise noted)



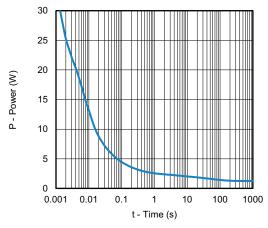
Source-Drain Diode Forward Voltage



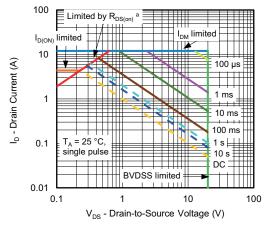
R_{DS(on)} vs. V_{GS} vs. Temperature



Threshold Voltage



Single Pulse Power



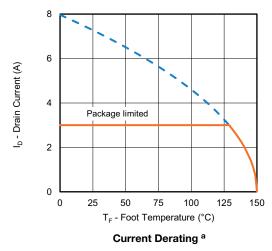
Safe Operating Area, Junction-to-Ambient

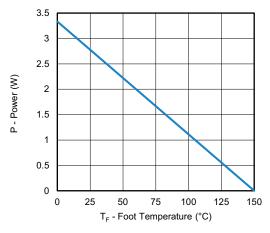
Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

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TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted)





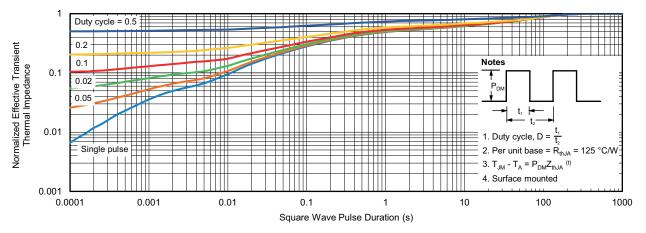
Power, Junction-to-Foot

Note

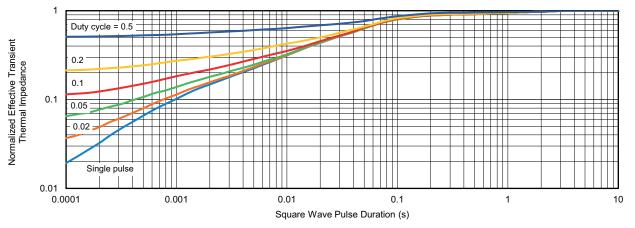
a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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